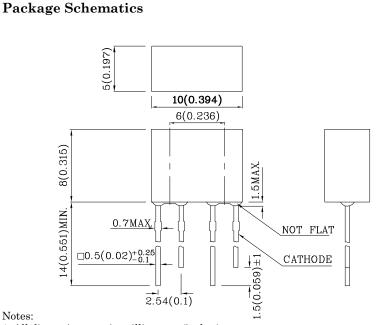


## Part Number: XEUY22D

### 5mm x 10mm LIGHT BAR

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- $\bullet$  RoHS compliant





1. All dimensions are in millimeters (inches).

2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.

3. Specifications are subject to change without notice.

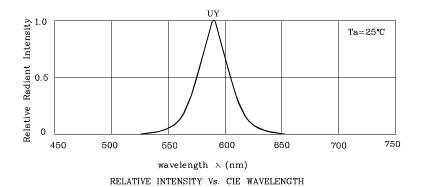
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UY (GaAsP/GaP)	Unit		
Reverse Voltage	$V_{\mathrm{R}}$	5	V		
Forward Current	$\mathbf{I}_{\mathrm{F}}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA		
Power Dissipation	PD	75	mW		
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C		
Storage Temperature	Tstg	$-40 \sim +85$	-C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

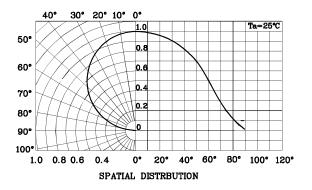
Operating Characteristics (T <sub>A</sub> =25°C)		UY (GaAsP/GaP)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	1.95	V	
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	2.5	V	
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λP	590*	nm	
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λD	588*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	$ riangle\lambda$	35	nm	
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	20	pF	

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =10mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XEUY22D	Yellow	GaAsP/GaP	Yellow Diffused	2*	3.8*	590*	120°

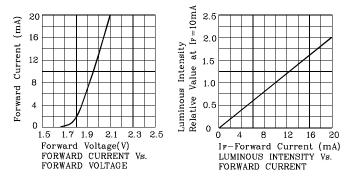
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



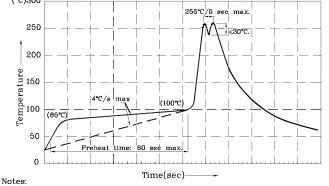




♦ UY



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components) (°C)300



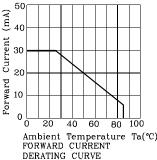
I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

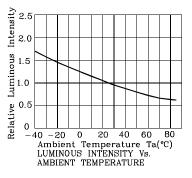
(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}$ C. 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass.





#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

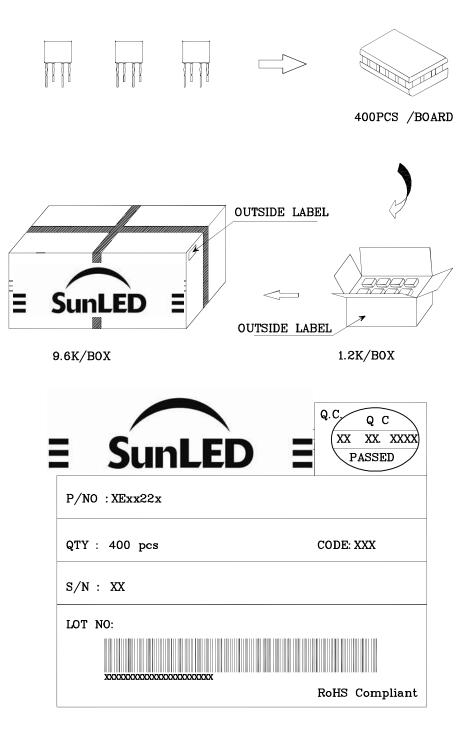
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



# PACKING & LABEL SPECIFICATIONS



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- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications. 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$

Jan 16,2014